

REV.	DESCRIPTION	DRAWN	CHECKED	APPROVED
A	NEW RELEASE	JLZ 03/24/16'	~	

**Description:**

RJ45 Offset & SMT, Reverse Type, Above PCB Height: 7.5mm

**Material:**

Housing Material: High Temp Nylon, LCP, UL94V-0

Contact Material: Phosphor Bronze T-0.35mm Thickness

Plating: Selective Gold Plating on Contact Area

Gold Plating Thickness: (Au 1u", 3u", 6u", 15u", 30u", 50u")

100u" Min. Matte Tin Plated on Soldering Area

50u" Min. Nickel Plated Overall

Shell: Copper Alloy, 0.25mm Thickness

**Electrical:**

Voltage Rating: 125 V AC RMS

Current Rating: 1.5 Amp

Contact Resistance: 30mΩ Max.

Insulation Resistance: 500MΩ Min. @ 500 VDC

Dielectric Withstanding Resistance: 1000 VAC RMS 50Hz, 1 Min.

**Mechanical:**

Durability : 750 Cycles Min.

**Environmental:**

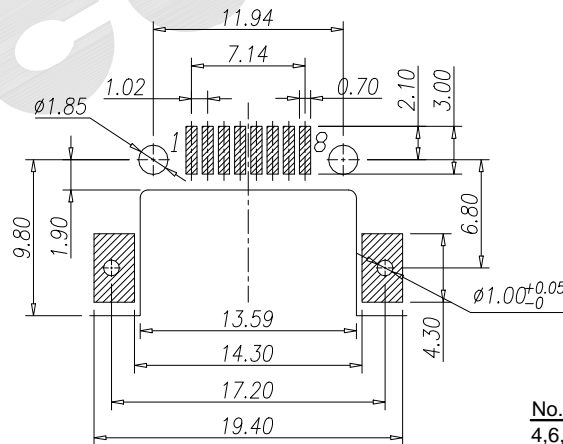
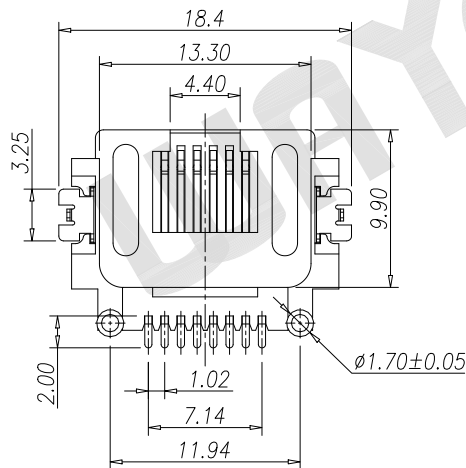
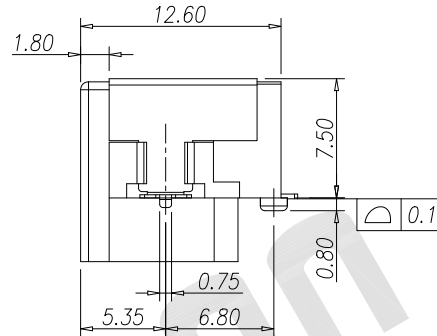
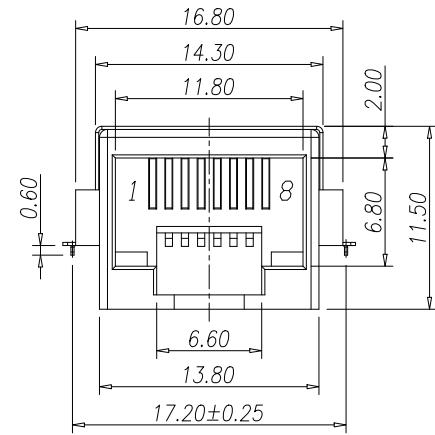
Storage Temperature : -40°C to +85°C

Operation Temperature: -40°C to +85°C

Reflow Soldering Temperature : 255°C to 265°C, 5-10 seconds

MJ7014T - X X X X X X X

No. of Positions	Positions Loaded	Shield	LED	Insulator Material	Contact Plating	Packing Style
4,6,8	2,4,6,8	0 - w/o Shield 1 - Shielded w/o EMI 2 - Shielded w/ EMI 3 - Half Shielded	0 - Without 1 - G/Y 2 - Y/G 3 - Other	1 - PBT 2 - PA66 3 - PA46 4 - LCP 5 - PA9T	1 - 1μ" 2 - 3μ" 3 - 6μ" 4 - 15μ" 5 - 30μ"	1 - Tape & Reel 2 - Plastic Tray



Recommend PCB Layout  
(Jack Top View)  
Tolerance: ±0.05mm

GENERAL TOLERANCE		ANGLE TOLERANCE		PROJECTION	UNIT	TITLE	
X.	±0.60	X.	±5°	mm		RJ45 Offset & SMT, w/ Half Shield	
.X	±0.38	.X	±3°			Reverse Type, Above PCB Height: 7.5mm	
.XX	±0.25	.XX	±2°				
DRAWING TYPE				CUSTOMER			
SCALE		1:1		SHEET		1 OF 1	
DRAWING NO.		MJ7014T- XXXXXXXX					

**WAYCONN CO.,LTD**